

## ABSTRACT

5 In a semiconductor device a substrate is formed in a rectangular shape  
having four edges along dicing lines, and a jetty portion is formed so as to  
surround an actuator element and an electrode pad for signal input and  
output. The jetty portion is a rectangular shape having four sides and each  
side continuously extends along each edge of the substrate in parallel. A  
foreign object generated when dicing process is performed, is prevented  
10 from attaching onto the actuator element and the electrode pad because  
close adhesion of a protecting tape is improved by the jetty portion.